

AMENDMENTS TO THE CLAIMS

1. (Previously presented) A substrate for a device package comprising:
 - a first portion of a package having a first surface, said first surface having a plurality of corner regions;
 - an intermediate metalization layer on said first surface of said first portion, said intermediate metalization layer extending into a first said corner region;
 - a second portion of said package on said first surface of said first portion, said intermediate metalization layer in said first corner region extending beyond said second portion to uniquely identify said first corner region.
2. (Previously presented) The substrate of Claim 1, said first and second portions comprising a ceramic.
3. (Previously presented) The substrate of Claim 1, said first portion comprising a layered ceramic portion containing electrical interconnections.
4. (Previously presented) The substrate of Claim 1, comprising a plating on said extending portion of said first portion.
5. (Previously presented) The substrate of Claim 1, comprising an electrical device electrically connected to portions of said intermediate metalization layer.
6. (Currently amended) The substrate of Claim 1, comprising an electrical device electrically connected to circuit portions of said intermediate metalization layer, said ~~corresponding portion~~ intermediate metallization in said first corner region electrically isolated from said circuit portions of said intermediate metalization layer electrically connected to said device.
7. (Original) The substrate of Claim 1, comprising an electrical device and a lid enclosing said device between said lid and said substrate.
8. (Previously presented) The substrate of Claim 1, said second portion having a void over said first corner region allowing visibility to said intermediate metalization layer.
9. (Original) The substrate of Claim 8, said void used to mechanically position said substrate.
- 10-19. (Canceled)

20. (Previously presented) A substrate for a device package comprising:
- a first portion of a package having a first surface, said first surface having a plurality of corner regions;
 - an intermediate metalization layer on said first surface of said first portion extending into a first said corner region;
 - a second portion of said package supported by said first surface of said first portion, said second portion not covering said first said corner region such that said first corner region is uniquely identified.
21. (Previously presented) The substrate of Claim 20, said first portion comprising a ceramic portion containing electrical interconnections.
22. (Previously presented) The substrate of Claim 20, said first portion comprising electrical connections on a second surface opposite said first surface.
23. (Previously presented) The substrate of Claim 20, comprising an electrical device electrically connected to circuit portions of said intermediate metalization layer, said corresponding portion of said intermediate metalization layer electrically isolated from said circuit portions of said intermediate metalization layer.
24. (Previously presented) The substrate of Claim 1, said second portion having a void over said corresponding portion of said metalization layer.
25. (Previously presented) The substrate of Claim 1, said first surface of said first portion having four said corner regions, wherein only one of said corner regions extends beyond said second portion.
26. (Previously presented) The substrate of Claim 20, said first portion comprising a ceramic portion.
27. (Previously presented) The substrate of Claim 20, said first portion comprising a polyamide.
28. (Previously presented) The substrate of Claim 20, said first portion comprising a plastic.